

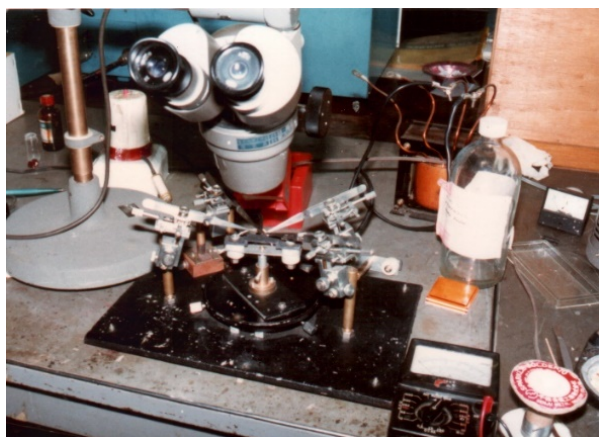
6 Assembly (dicing, wire bonding, soldering) and test



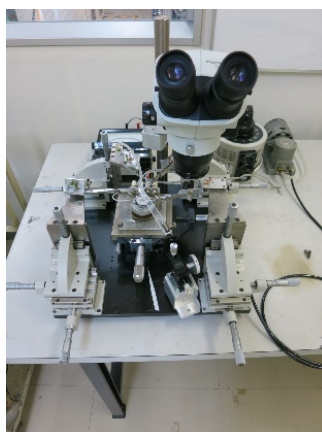
Dicing machine (chip separation from wafer)



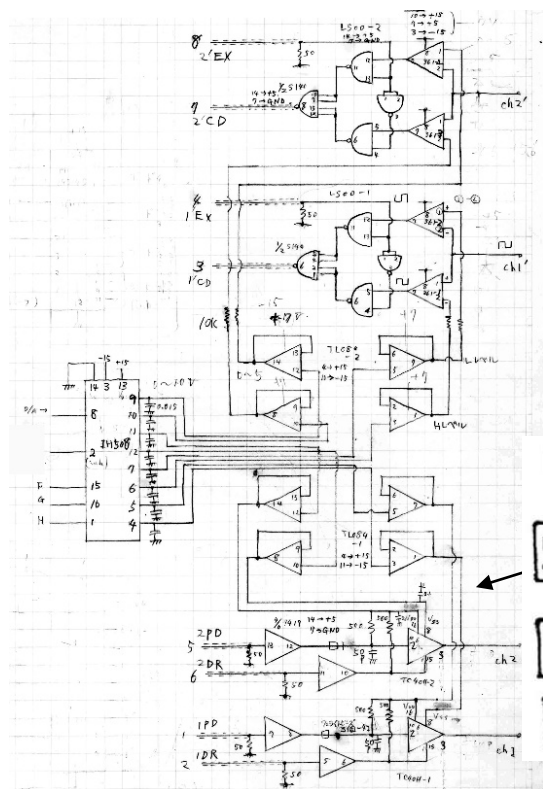
Ultrasonic wire bonder (exhibited)



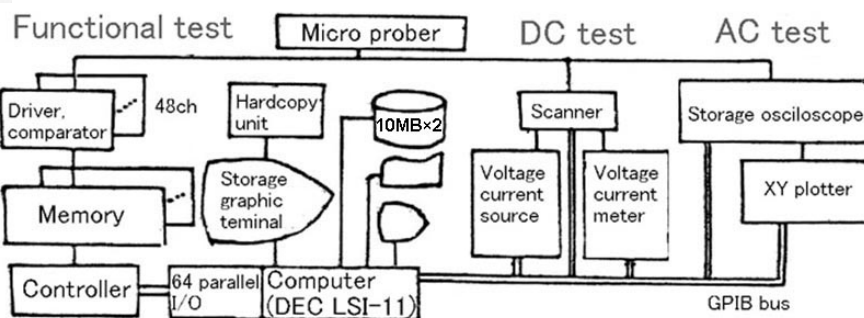
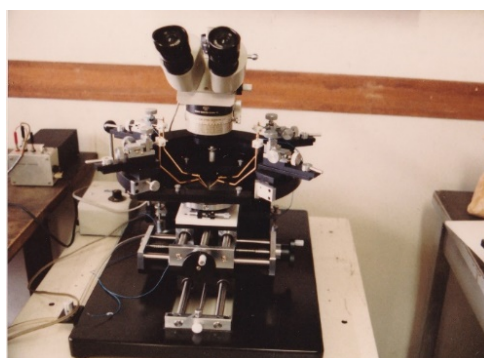
Micro soldering machine using cream solder (right exhibited)



Microprober for testing



Pin electronics for IC tester (2ch)



IC test system